



PK790 (v1.0) Apr 26, 2016

100% Material Declaration Data Sheet for RF1761

Average Weight : 30.2100 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon Die					0.532613	1.763%
	Silicon	7440-21-3	100.00	basis	0.532613	
Bump					0.026037	0.086%
	Consigned				0.026037	
Underfill					0.060000	0.199%
	Bisphenol F/ epichlorohydrin	9003-36-5	20.00	basis	0.012000	
	Phenolic resin	trade secret	15.00	basis	0.009000	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.003000	
	Amine type accelerator	trade secret	5.00	basis	0.003000	
	Silicon dioxide	60676-86-0	51.50	basis	0.030900	
	Carbon black	1333-86-4	1.00	basis	0.000600	
Solder paste					0.009116	0.030%
	Tin	7440-31-5	63.00	metal	0.005743	
Capacitor 1					0.006880	0.023%
	Lead	7439-92-1	37.00	metal	0.002125	
	Barium	12047-27-7	88.86	Ceramic	0.006113	
	Manganese	1313-13-9	1.43	Ceramic	0.000098	
	Nickel	7440-02-0	4.29	Internal Electrode	0.000295	
	Copper	7440-50-8	0.70	Termination	0.000048	
	Boron	1303-86-2	0.01	Termination	0.000001	
	Nickel	7440-02-0	3.57	Plating	0.000246	
Capacitor 2					0.003800	0.013%
	Tin	7440-31-5	0.90	Plating	0.000062	
	Lead	7439-92-1	0.24	Plating	0.000017	
	Barium	12047-27-7	88.86	Ceramic	0.003377	
	Manganese	1313-13-9	1.43	Ceramic	0.000054	
	Nickel	7440-02-0	4.29	Internal Electrode	0.000163	
	Copper	7440-50-8	0.70	Termination	0.000027	
Capacitor 3					0.000313	0.001%
	Glass oxide	65997-17-3	0.01	Termination	0.000001	
	Nickel	7440-02-0	3.57	Plating	0.000136	
	Tin	7440-31-5	0.86	Plating	0.000033	
	Lead	7439-92-1	0.29	Plating	0.000011	
	Barium	12047-27-7	71.29	Ceramic	0.000223	
Capacitor 4					0.000920	0.003%
	Manganese	1313-13-9	10.43	Ceramic	0.000033	
	Nickel	7440-02-0	2.00	Internal Electrode	0.000006	
	Copper	7440-50-8	11.57	Termination	0.000036	
	Boron	1303-86-2	0.21	Termination	0.000001	
	Nickel	7440-02-0	1.80	Plating	0.000006	
	Gold	7440-57-5	2.70	Plating	0.000008	
	Barium	12047-27-7	72.40	Ceramic	0.000666	
Heat sink					20.130000	66.634%
	Manganese	1313-13-9	10.60	Ceramic	0.000098	
	Nickel	7440-02-0	4.00	Internal Electrode	0.000037	
	Copper	7440-50-8	5.80	Termination	0.000053	
	Glass oxide	65997-17-3	0.20	Termination	0.000002	
	Nickel	7440-02-0	2.66	Plating	0.000024	
	Tin	7440-31-5	3.99	Plating	0.000037	
Heat sink adhesive					0.131000	0.434%
	Copper	7440-50-8	1.65	Main material	0.332145	
Solder ball					0.091700	0.434%
	Aluminium Oxide Al2O3	1344-28-1	70.00	Main material	0.091700	
Solder ball					1.675163	5.545%
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Main material	0.039300	
Solder ball					1.675163	5.545%
	Tin	7440-31-5	63.00	Main material	1.055353	
	Lead	7439-92-1	37.00	Main material	0.619810	
	Copper	7440-50-8	36.96		7.634158	
	Tin	7440-31-5	0.27		3.029997	
	Lead	7439-92-1	0.16		0.020612	
Substrate					0.012215	25.270%
	Core	N/A	40.35		0.012215	
	ABF	N/A	18.16		3.080383	
	Solder Mask	N/A	1.38		1.386363	
					0.105351	

Revision History

Date	Version	Description of Revisions
4/26/2016	1.0	Initial Xilinx release.

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